| 4 2 annealing same (substrate or wafer) same insulation same (Second adj side) 5 858 (anneal\$4 or (heat adj treatment)) same sublim\$5 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | L Number | Hits | Search Text | DB | Time stamp |
|---|----------|-------|--|-----------|------------------|
| 2 annealing same (substrate or wafer) same insulation same SPC; JPC; DERWENT; IBM_TDB USPAT; US-PGPUB; EPC; JPC; JPC; DERWENT; IBM_TDB USPAT; US-PGPUB; EPC; JPC; JPC; DERWENT; IBM_TDB USPAT; US-PGPUB; EPC; JPC; JPC; JPC; JPC; JPC; JPC; JPC; J | | | annealing with (substrate or wafer) with insulation with | USPAT; | 2004/05/27 11:35 |
| 2 annealing same (substrate or wafer) same insulation same USPAT; USPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPGPUB; EPO; JPO; DERWENT; IB | | | (second adj side) | | • |
| 2 annealing same (substrate or wafer) same insulation same (second adj side) 2004/05/27 11 USPAT; USPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; I | | | | | |
| 2 annealing same (substrate or wafer) same insulation same (sucond adj side) 2004/05/27 11 2004/05/27 | | | | DERWENT; | |
| Second adj side US-PGPUB; EPC; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; IMB_TDB USPAT; US-PGPUB; IMB_TDB USPAT; US-PGPUB; IMB_TDB USPAT; I | j | | | IBM_TDB | |
| See | 4 | 2 | annealing same (substrate or wafer) same insulation same | USPAT; | 2004/05/27 11:34 |
| DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; ISM_TDB USP | | | (second adj side) | US-PGPUB; | |
| See | | | | EPO; JPO; | |
| Second or buttom) adj side) Second or buttom) adj side) with ((second or buttom) adj side) Second or buttom) | | | | DERWENT; | |
| 1 | | | | | |
| 6 1 (anneal\$4 or (heat adj treatment)) same sublim\$5 same (insulation adj film) 7 66 (insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side) 9 0 (((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side) with (second or buttom) adj side | 5 | 858 | (anneal\$4 or (heat adj treatment)) same sublim\$5 | | 2004/05/27 11:37 |
| 1 | | | | | |
| 1 (anneal\$4 or (heat adj treatment)) same sublim\$5 same (insulation adj film) 7 66 (insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side) 9 0 (((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side) with ((second or buttom)) adj side) with (second or buttom)) adj side) with (s | | | | | |
| 1 (anneal\$4 or (heat adj treatment)) same sublim\$5 same (insulation adj film) 66 (insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side) 9 0 (((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper), DERWENT; IBM_TDB (USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((second or buttom) adj side)) and (etch\$4 with (first or upper), DERWENT; IBM_TDB ((second or buttom) adj side)) and (etch\$4 with (first or upper), DERWENT; IBM_TDB ((second or buttom) adj side)) and (etch\$4 with (first or upper), DERWENT; IBM_TDB (Second or buttom) adj side)) and (etch\$4 with (first or upper), DERWENT; IBM_TDB (US-PGPUB; EPO; JPO; DERWENT; IBM_TDB (US-PGPUB; EPO; JPO; DERWENT; IBM_TDB (US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; | | | | DERWENT; | |
| (insulation adj film) (insulation adj film) (insulation adj film) (insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side) ((second or buttom) adj side) ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) and annneal\$5 ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper) upper)) ((insulation adj film) with ((first or upper) adj side) with (upper) (upper)) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) upper) upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) upper) upper) upper) ((insulation adj film) with ((first or upper) adj side) with (upper) upper) uppe | | | | | |
| FPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; | 6 | 1 | | | 2004/05/27 11:50 |
| 7 66 (insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side) 9 0 (((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) 8 47 ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) 10 35 sublimation with ((second or buttom) near3 substrate) 10 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; | | | (insulation adj film) | | |
| To Go (insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; ((second or buttom) adj side)) and (etch\$4 with (first or upper)) and annneal\$5 US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGPUB | | | | | |
| 7 66 | | | | | |
| 9 0 (((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) adj side) with ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) US-PGPUB; EPO; JPO; DERWENT; IBM_TDB (US-PGPUB; EPO; JPO; DERWENT; IBM_TDB (US-PGPUB; EPO; JPO; DERWENT; IBM_TDB (US-PGPUB; IBM_TDB) (US-PGPUB; IBM_TDB | | | | | |
| 9 0 (((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper))) and annneal\$5 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; ((second or buttom) adj side)) and (etch\$4 with (first or upper)) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB; | 7 | 66 | | | 2004/05/27 11:52 |
| 9 0 (((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper))) and annneal\$5 8 47 ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) 10 35 sublimation with ((second or buttom) near3 substrate) DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US | | | ((second or buttom) adj side) | | |
| 9 0 (((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper))) and annneal\$5 8 47 ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) 10 35 sublimation with ((second or buttom) near3 substrate) IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; | | | | | |
| 9 (((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper))) and annneal\$5 8 47 ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) 10 35 sublimation with ((second or buttom) near3 substrate) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGPUB | | | | | |
| ((second or buttom) adj side)) and (etch\$4 with (first or upper))) and annneal\$5 8 47 ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) 10 35 sublimation with ((second or buttom) near3 substrate) US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; | | | | | |
| upper))) and annneal\$5 8 47 ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) 10 35 upper))) ((insulation adj film) with ((first or upper) adj side) with (USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; | 9 | 0 | | | 2004/05/27 11:54 |
| 8 47 ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) 10 35 sublimation with ((second or buttom) near3 substrate) DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; | | | | | |
| 8 47 ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; Sublimation with ((second or buttom) near3 substrate) USPAT; US-PGPUB; | | | upper))) and annneal\$5 | | |
| 8 47 ((insulation adj film) with ((first or upper) adj side) with ((second or buttom) adj side)) and (etch\$4 with (first or upper)) 10 35 ((insulation adj film) with ((first or upper) adj side) with (USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGPUB; | | | | | |
| ((second or buttom) adj side)) and (etch\$4 with (first or upper)) US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGPUB; | | 47 | //: . 1 / | | |
| upper)) 10 35 upper)) EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; | 8 | 47 | | , | 2004/05/27 11:57 |
| DERWENT; IBM_TDB USPAT; US-PGPUB; 2004/05/27 12 | | | 1 | | |
| 10 35 sublimation with ((second or buttom) near3 substrate) IBM_TDB USPAT; US-PGPUB; 2004/05/27 12 | | | upper)) | | |
| 10 35 sublimation with ((second or buttom) near3 substrate) USPAT; US-PGPUB; 2004/05/27 12 | | | | • | |
| US-PGPUB; | 10 | 25 | sublimation with //second or huttom) near? substrate) | _ | 2004/05/27 42:05 |
| | 10 | 33 | submittation with ((second of buttorn) hears substrate) | | 2004/05/27 12:05 |
| | | | | | |
| DERWENT; | | | | | |
| IBM_TDB | | | | | |
| · · · · · · · · · · · · · · · · · · · | 11 | 781 | sublimation and 438 clas | | 2004/05/27 13:00 |
| US-PGPUB; | ., | , 0 1 | | | 2007/00/2/ 10.00 |
| EPO; JPO; | | | | | |
| DERWENT; | 1 | | | | |
| IBM_TDB | İ | | | | |
| | 12 | 729 | (sublimation and 438.clas.) and substrate | | 2004/05/27 12:57 |
| US-PGPUB; | | | , | | |
| EPO; JPO; | l | | | | |
| DERWENT; | l | İ | | | |
| IBM_TDB | ŀ | | | | |
| | 13 | 199 | (sublimation with (substrate or wafer)) and 438.clas. | | 2004/05/27 13:01 |
| US-PGPUB; | ļ | | . , , , , , , , , , , , , , , , , , , , | • | |
| EPO; JPO; | 1 | | | | |
| DERWENT; | 1 | | | | |
| IBM_TDB | ĺ | | | | |
| 146 | 16 | 781 | sublimation and 438/\$.ccls. | | 2004/05/27 13:01 |
| US-PGPUB; | | | | • | |
| EPO; JPO; | | | | | |
| DERWENT; | | | | | |
| IBM_TDB | | | | IBM_TDB | |

| 17 | 199 | (sublimation with (substrate or wafer)) and 438/\$.ccls. | USPAT; | 2004/05/27 13:18 |
|----|-----|---|-----------|------------------|
| | | | US-PGPUB; | |
| l | | | EPO; JPO; | |
| İ | | | DERWENT; | |
| | | | IBM TDB | |
| 18 | 15 | (sublimation with (substrate or wafer)) same insul\$5 and | USPAT; | 2004/05/27 13:19 |
| i | 1 | 438/\$.ccls. | US-PGPUB; | |
| i | | | EPO; JPO; | |
| | | | DERWENT; | |
| 1 | | | IBM_TDB | |